

NANOSTRUCTURED THIN FILMS FOR THERMOELECTRICS APPLICATIONS

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- 1 - Generality on thermoelectricity and materials**
- 2 - Toward the nanostructuration**
- 3 - Influence of thin films nanostructuration on TE properties**
- 4 - Conclusions**

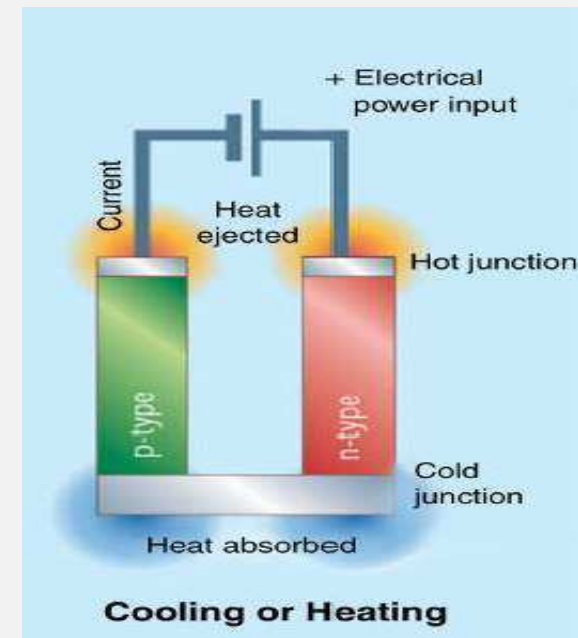
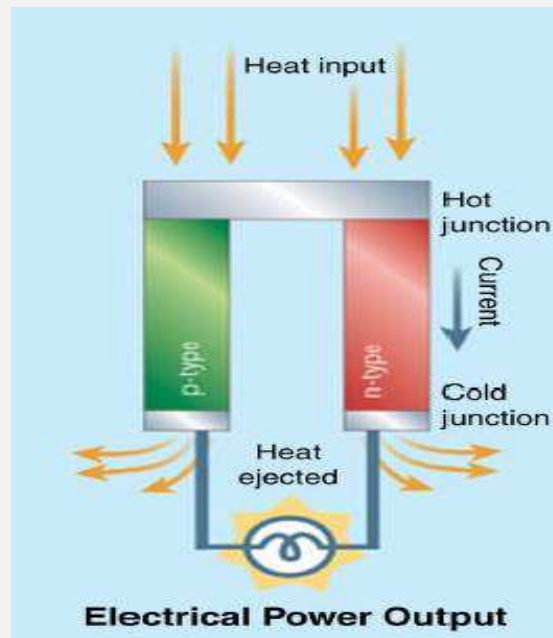
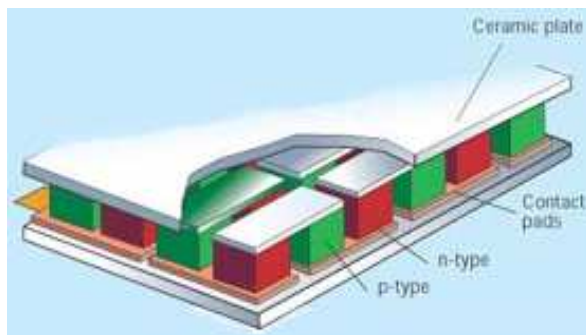
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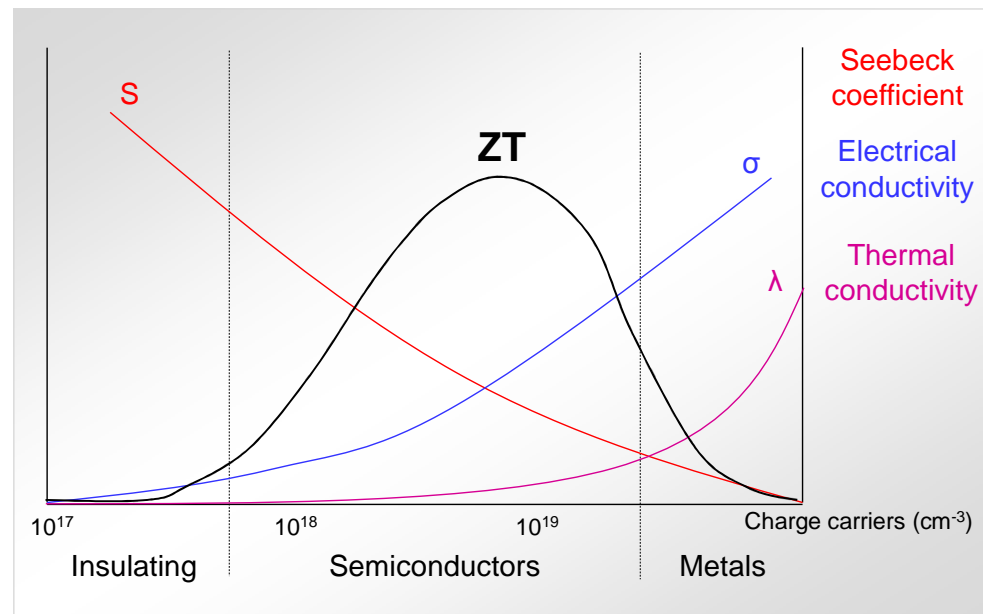
Standard structure of a thermoelectric device



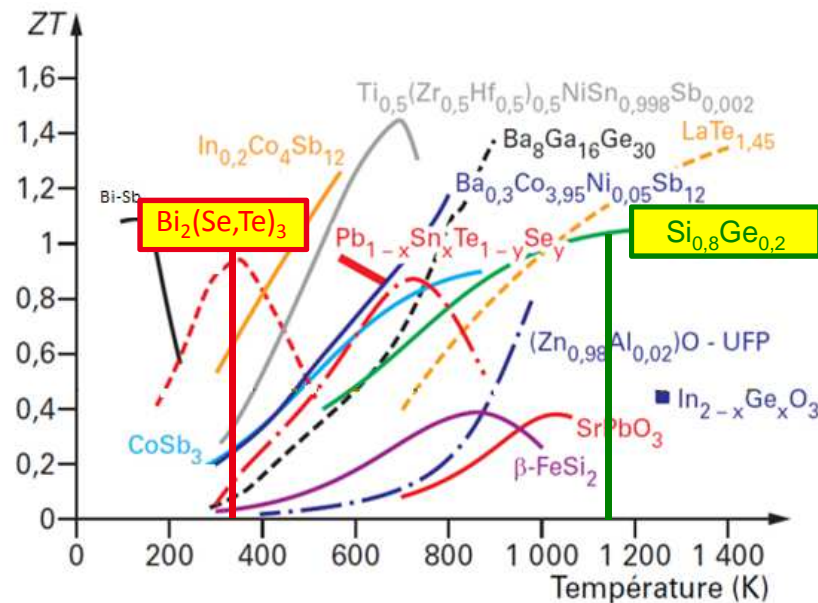
Effect	Seebeck effect	Peltier effect
Principle	Temperature gradient induces Seebeck voltage	Electrical current induces cooling/heating effect
Applications	<ul style="list-style-type: none"> → Power generation → Thermal flow sensor 	<ul style="list-style-type: none"> → Cooling → Thermal management

DEFINITION OF FIGURE OF MERIT

- Three important properties for TE materials :
 - S = Seebeck coefficient ($\mu\text{V.K}^{-1}$)
 - σ = electrical conductivity (S.m^{-1})
 - λ = thermal conductivity ($\text{W.m}^{-1}\text{.K}^{-1}$)
- Definition of the dimensionless figure of merit $ZT = \frac{\sigma \times S^2}{\lambda} T$

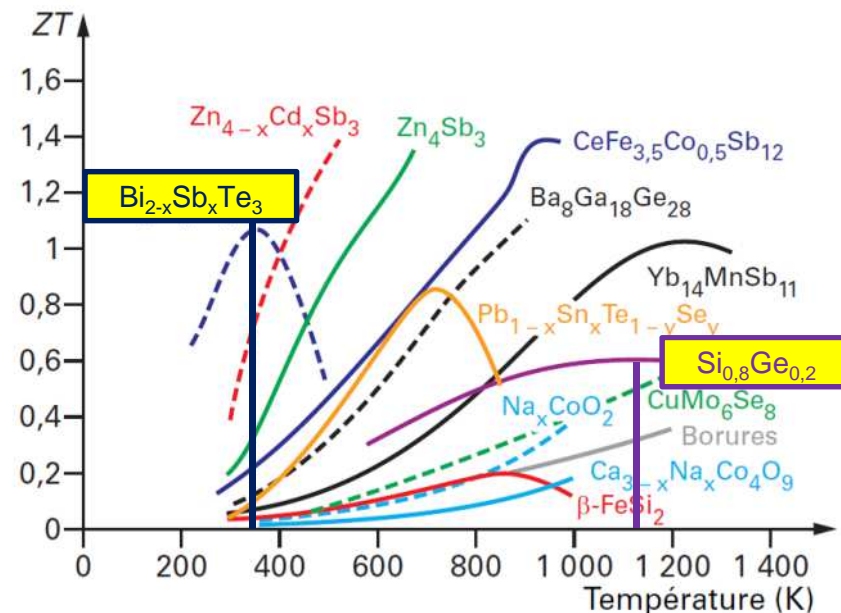


→ **Best TE materials correspond to highly doped semiconductors**



N-type

- H-H: TiNiSn & dérivés (430 °C max)
- skutterudites: CoSb₃ & dérivés (530 °C max)
- clathrates: Ba₈Ga₁₆Ge₃₀ (630 °C max)
- Pb_{1-x}Sn_xTe_{1-y}Se_y (530 °C max)
- Si_{0.8}Ge_{0.2} (1000 °C max)
- Mg₂Si & dérivés (530 °C max)



P-type

- Zn₄Sb₃ & dérivés (400 °C max)
- skutterudites: CeFe_{3.5}Co_{0.5}Sb₁₂ (710 °C max)
- clathrates: Ba₈Ga₁₆Ge₃₀ (630 °C max)
- Pb_{1-x}Sn_xTe_{1-y}Se_y (530 °C max)
- Si_{0.8}Ge_{0.2} (1000 °C max)
- MnSi_{1.75-x} (T_{max} mal connue)

→ A lot of TE materials, function of temperatures and applications

- Development of TE materials dictated by our applications at thin films scale:
 - environment: microelectronic
 - applications: thermal sensors and power generation
 - temperature: room temperatures (20 - 150 °C)
- Use of green materials (non toxic, abundant, non expensive...)
- Use of nanostructuration to increase TE performances
- Materials deposition compatible with microelectronic technology

→ **Silicon and Silicon-Germanium alloys based materials:**

- well-known in microelectronic environment
- green materials
- possibility to use nanostructuration
- deposition technique compatible with microelectronic technology
- but low ZT at room temperature...

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- To increase $ZT = \frac{\sigma \times S^2}{\lambda} T$, two possibilities :
 - increase of power factor σS^2
 - decrease of thermal conductivity λ
- About twenty years ago, Hicks and Dresselhaus have introduced the concept of electron and holes quantum confinement in low dimensional materials which could increase the ZT significantly *

→ Introduction of nanostructuration for TE

- Increase of power factor σS^2

→ Mott's equation:
$$S = -\frac{\pi^2}{3} \frac{k_B}{e} k_B T \left(\frac{\partial \ln \sigma(E)}{\partial E} \right)_{E_F}$$

→ Expression of σ :
$$\sigma(E) = \mu(E)n(E)e$$

→ So:
$$S = \frac{\pi^2}{3} \frac{k_B}{e} k_B T \left[\frac{1}{\mu(E_F)} \left(\frac{\partial \mu(E)}{\partial E} \right)_{E_F} + \frac{1}{n(E_F)} \left(\frac{\partial n(E)}{\partial E} \right)_{E_F} \right]$$

derivative in energy
of state density

derivative in energy
of mobility

→ Increase of power factor can be obtained by increasing the electron state density near Fermi level (increase of electron quantum confinement)

→ **Increase of power factor by imposing judicious defaults at the electronic structure (increase of carriers number for example)**

- Decrease of the thermal conductivity λ

→ Thermal conductivity: sum of two terms:

$$\lambda = \lambda_e + \lambda_p$$

with λ_e electronic thermal conductivity
 λ_p lattice thermal conductivity (phonons)

→ According to the Wiedemann-Franz law:

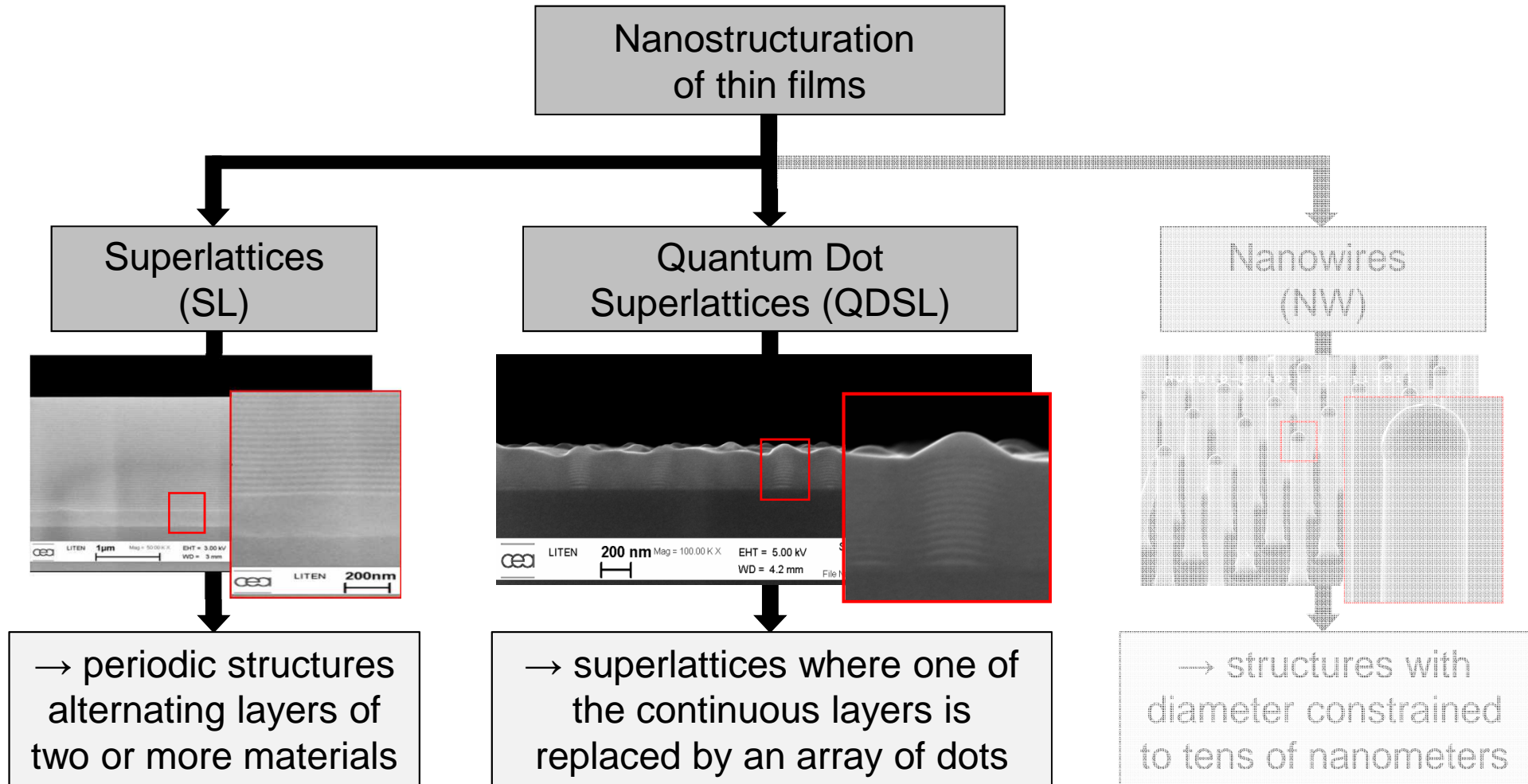
$$\lambda_e = L_0 \times \sigma \times T$$

with L_0 Lorenz constant ($2,44 \cdot 10^{-8} \text{ W} \cdot \Omega \cdot \text{K}^{-2}$)
 σ electrical conductivity
 T temperature

→ Decrease of the lattice thermal conductivity λ_p

→ **Decrease of thermal conductivity by increasing phonons scattering**

- Several kinds of nanostructuration for thin films thermoelectric materials



- Growth by Reduced Pressure (RP)CVD of thin films nanostructured materials, compatible with microelectronic environment
- Progress on thin films nanostructured materials

2007

- GEN1 - Si/SiGe SuperLattices

G. Savelli et al., *J. Micromech. Microeng.* 18 (2008)

2008

2009

- GEN2 - Ge/SiGe Quantum Dot Superlattices

D. Hauser et al., *ECT10, Italy* (2010)

D. Hauser et al., *Thin Solid Films* 520 (2012)

G. Savelli et al., *AIP Conf. Proc.* 1449 (2012)

2010

2011

2012

- GEN3 - Silicide Quantum Dot Superlattices

2013

- QDSL TiSi_x / SiGe

- QDSL MoSi_x / SiGe

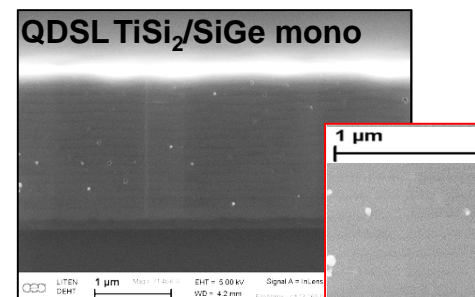
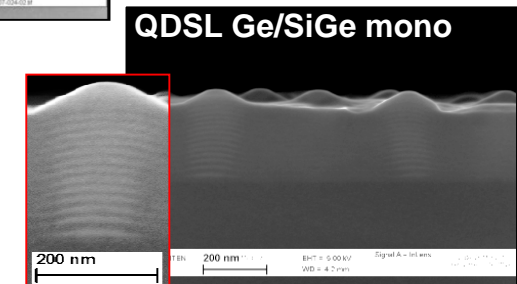
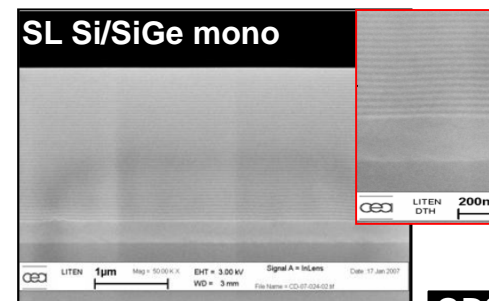
2014

S. Silveira Stein et al., *IEEE Nano, Canada* (2014)

G. Savelli et al., *Nanotechnology* 26 (2015)

2015

G. Savelli et al., *Superlattice Microst.* 92 (2016)



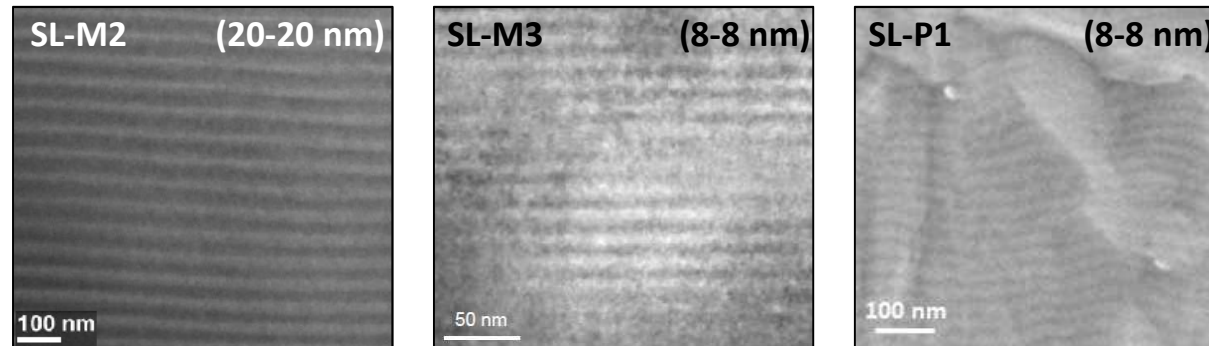
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- TEM views of Si/SiGe SL with different periods and structures



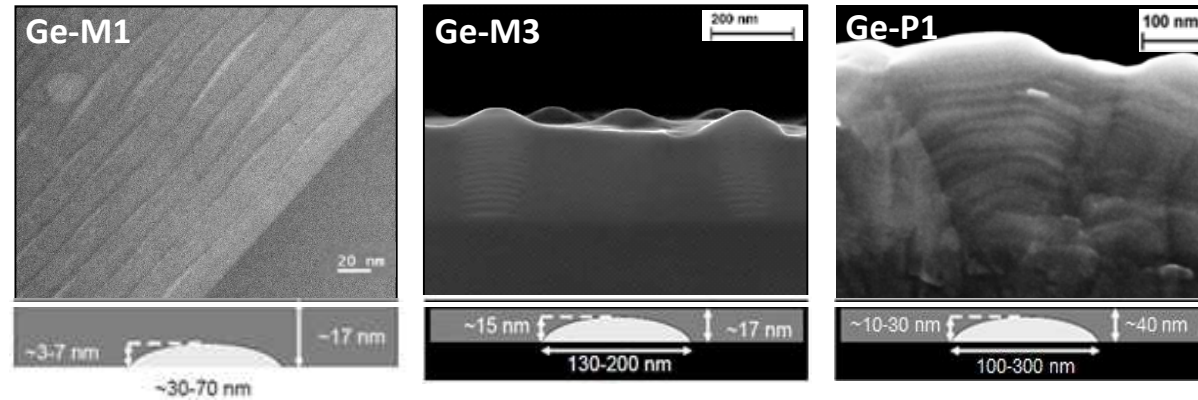
- Influence of undoped SL on thermal conductivity

Sample	Structure	Type	Si/SiGe SL period (nm)	Ge content (%)	λ_{\perp} (W.m ⁻¹ .K ⁻¹)
SL-M1	mono	SL	40-40 (x4)	~ 15	14
SL-M2	mono	SL	20-20 (x8)	~ 15	7
SL-M3	mono	SL	8-8 (x20)	~ 15	5.4
SL-M4	mono	SL	4-8 (x25)	~ 15	5
SL-P1	poly	SL	8-8 (x20)	~ 15	2.8

→ **Decrease of thermal conductivity by decreasing SL period**

GE-BASED QUANTUM DOT SUPERLATTICES (QDSL)

- TEM and SEM views of Ge-based QDSL with different periods and structures



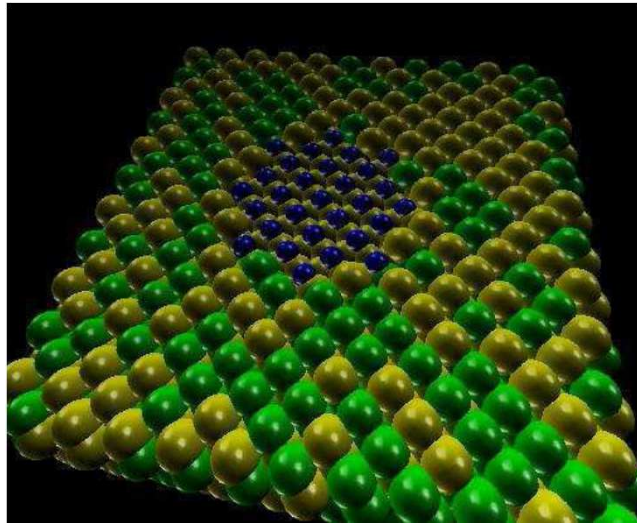
- Influence of p-doped QDSL on electrical and thermal conductivities

Sample	Structure	Type	Thickness / width of dots (nm)	Ge content (%)	$\rho_{ }$ (m Ω .cm)	λ_{\perp} (W.m ⁻¹ .K ⁻¹)
Ge-MR	mono	REF	-	7.7	2.2	10.5
Ge-M1	mono	QDSL	3-7 / 30-70 (x15)	7.6	3.8	6.1
Ge-M2	mono	QDSL	12 / 100-170 (x15)	9.4	2.7	6
Ge-M3	mono	QDSL	15 / 130-200 (x15)	11.8	1.9	5.3
Ge-PR	poly	REF	-	13.3	3.6	4.5
Ge-P1	poly	QDSL	10-30 / 100-300 (x15)	14.2	3	4

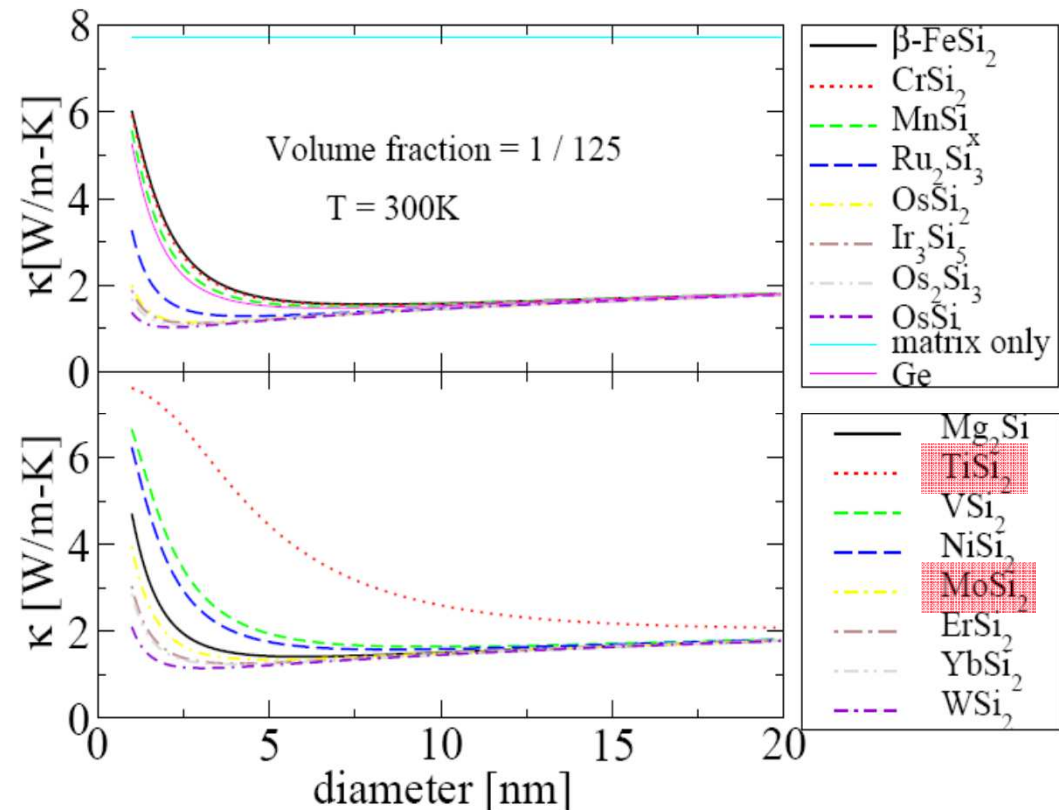
→ **Decrease of thermal conductivity thanks to the nanodots inclusion**

SILICIDE-BASED QUANTUM DOT SUPERLATTICES (QDSL)

- New nanomaterial concept: *nano-inclusions of metallic silicide in SiGe matrix* *
- Use of ab-initio phonon transport calculations to choose the good silicide



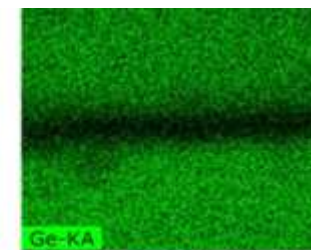
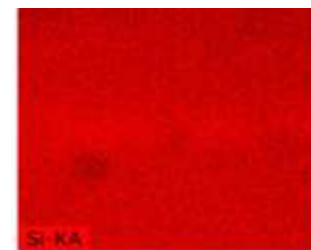
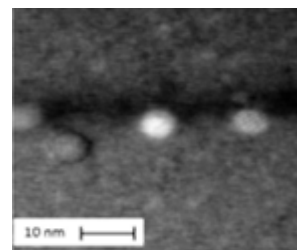
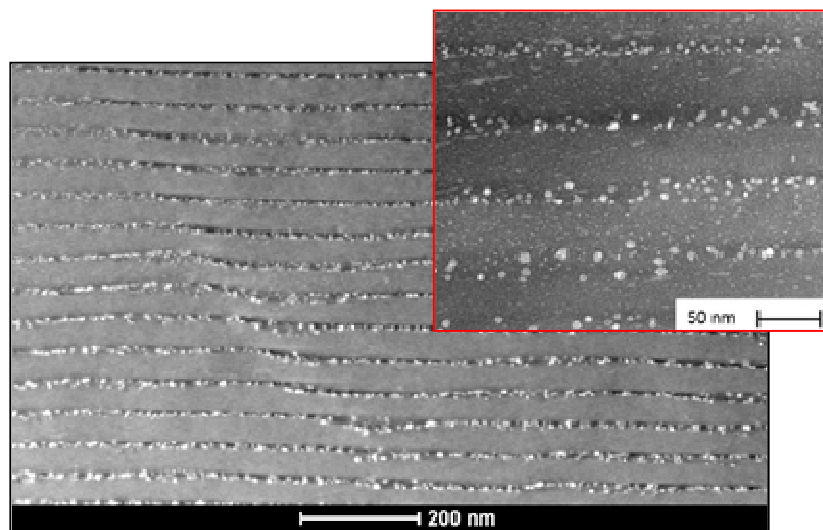
Example of a nano-inclusion embedded in a SiGe matrix.



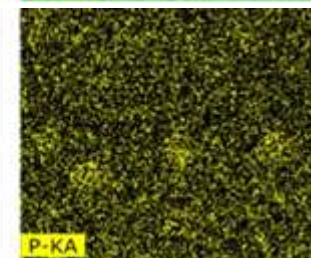
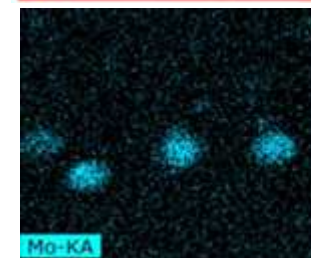
Evolution of the thermal conductivity as a function of nature and size of nanoparticles.

→ **High performances predicted by theory for these new materials**

- STEM views and TE properties of monocrystalline Mo-based QDSL



*Energy Dispersive
X-ray Spectroscopy
(EDS) analyses
(Mo-M1 sample).*

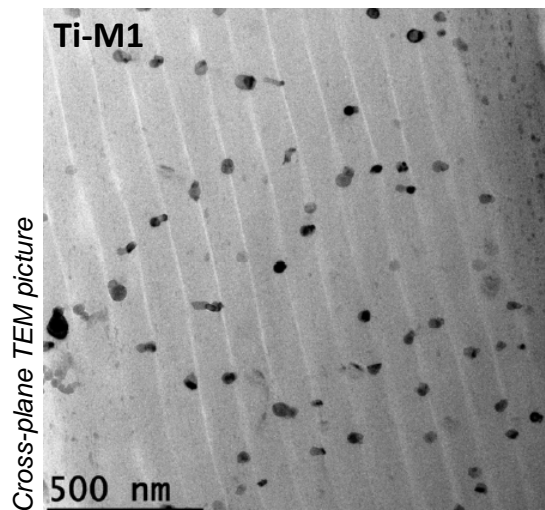


- Influence of n-doped QDSL on electrical and thermal conductivities

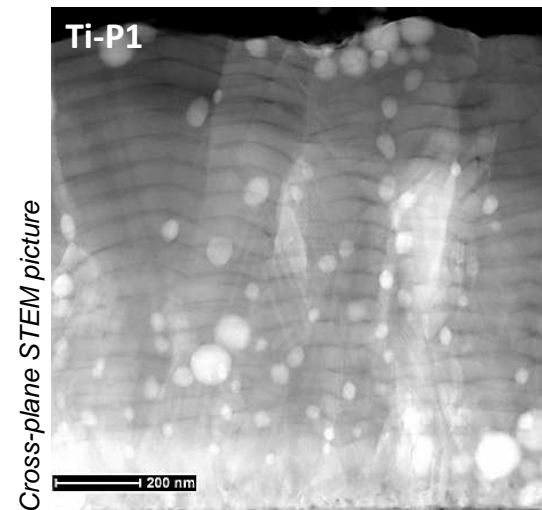
Sample	Structure	Type	Dots size - spacing (nm)	Ge content (%)	$\rho_{ }$ (m Ω .cm)	λ_{\perp} (W.m ⁻¹ .K ⁻¹)
Mo-MR	mono	REF	-	10	1.35	13
Mo-M1	mono	QDSL	5 - 50	10	1.4	9,5

- TEM views and TE properties of n-doped Ti-based QDSL

Monocrystalline $\text{TiSi}_2/\text{SiGe}$ QDSL



Polycrystalline $\text{Ti}_3\text{Si}/\text{SiGe}$ QDSL



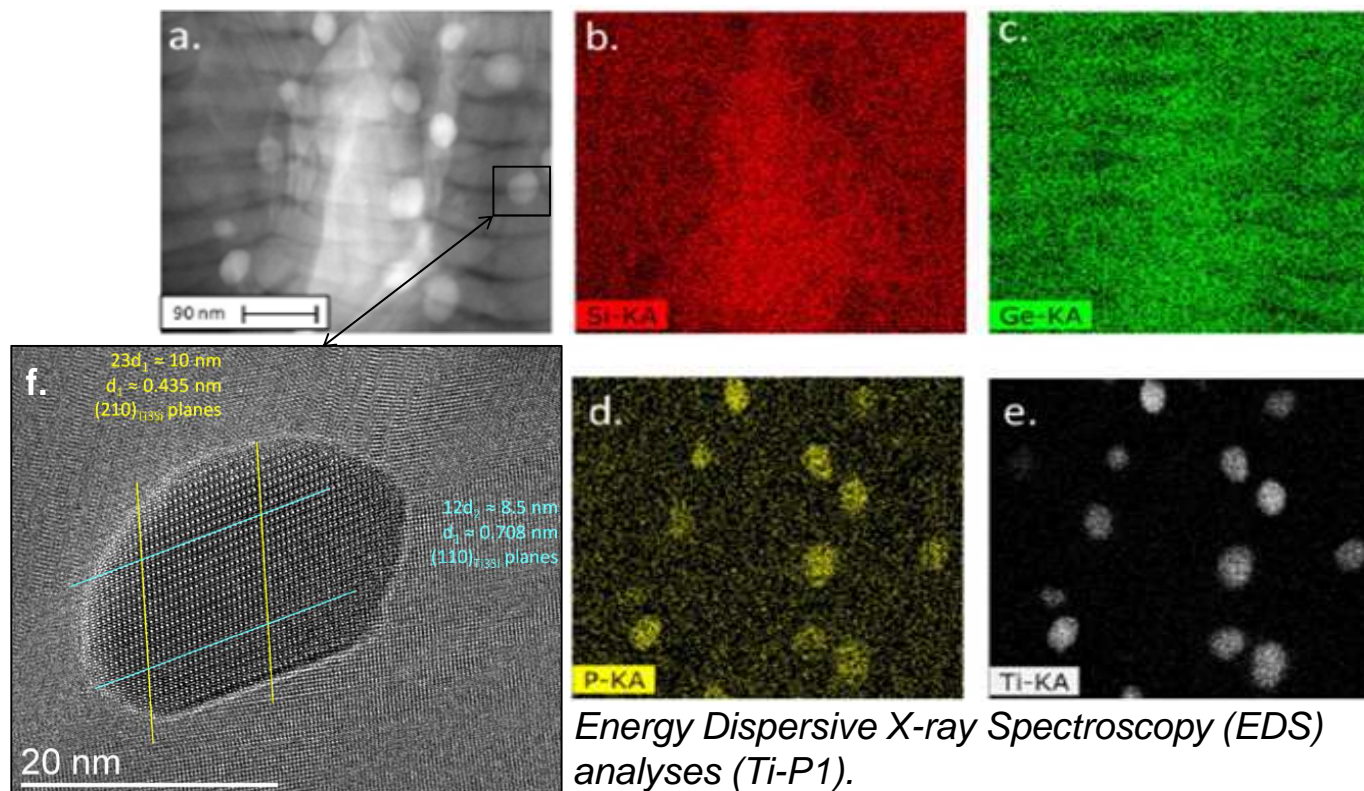
Sample	ρ_{\parallel} (m Ω .cm)	S_{\parallel} ($\mu\text{V}/\text{K}$)	PF_{\parallel} ($\mu\text{W}/\text{cm}/\text{K}^2$)	λ_{\perp} (W/m 2 /K)
Ti-MR (ref)	2,7	-104	4	8,5
Ti-M1	2,6	-190	14	6,8

Sample	ρ_{\parallel} (m Ω .cm)	S_{\parallel} ($\mu\text{V}/\text{K}$)	PF_{\parallel} ($\mu\text{W}/\text{cm}/\text{K}^2$)	λ_{\perp} (W/m 2 /K)
Ti-PR (ref)	11	-130	1,5	4,6
Ti-P1	12,5	-215	3,7	4,2

→ increase of TE properties thanks to the nanostructuration
 → in good agreement with the theoretical predictions

TiSi₂-BASED QUANTUM DOT SUPERLATTICES (QDSL)





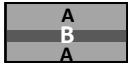

- Chemical analyses of TiSi₂-based QDSL
 - dots accumulation at the grains boundaries
 - dopant accumulation near the QD coming from a high affinity between the metal silicide and the dopant atoms



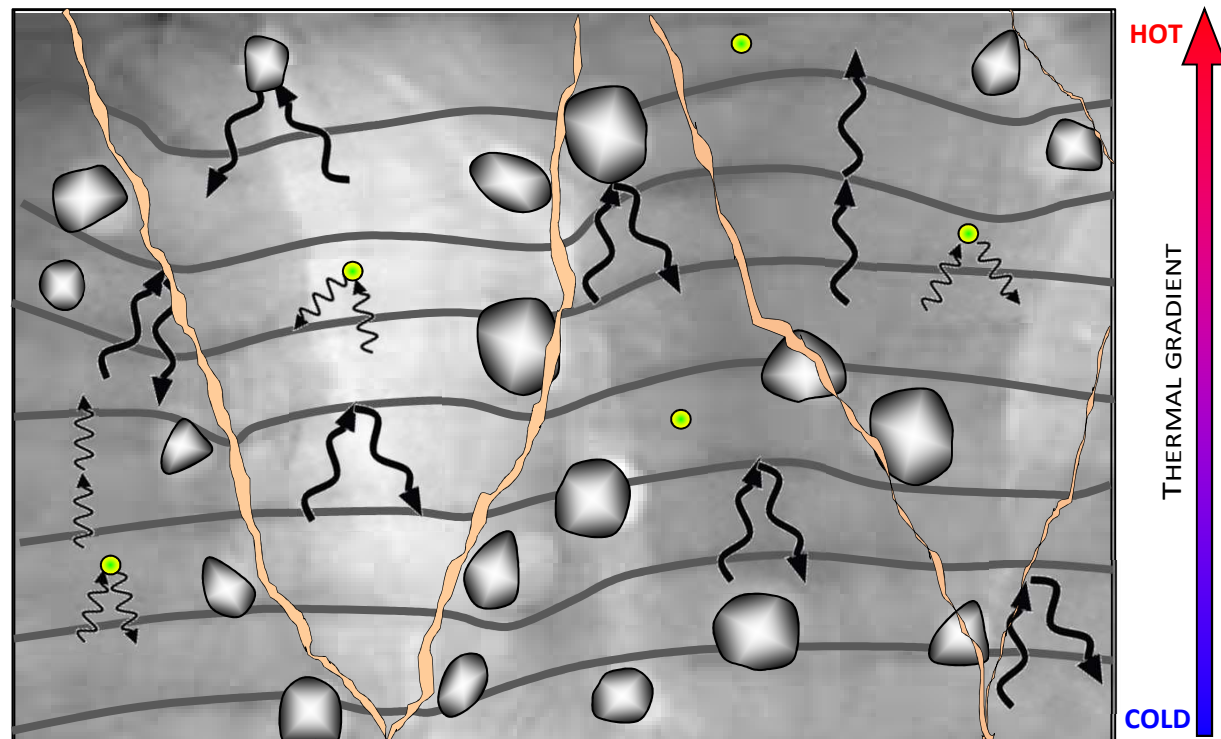
DIFFERENT MECHANISMS OF PHONON SCATTERING

- « classical » scattering mechanisms:
 - grains boundaries diffusion (for polycrystalline materials)
 - impurities diffusion
- « addition » of phonon scattering mechanisms thanks to nanostructuration:
 - scattering with interfaces
 - scattering with nanoparticles

Legend

-  Low wavelength phonons
-  High wavelength phonons
-  Grains boundaries
-  Impurities
-  Interfaces
-  Nanoparticles

Example with Ti-P1 sample.



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- Growth of several thin films nanostructures, superlattices and quantum dot superlattices, monocrystalline and polycrystalline
- Influence of thin films nanostructuration on thermoelectric properties has been highlighted
- In every instance, a decrease of thermal conductivity has been measured
- Specific growth mechanisms have been obtained for silicide-based QDSL (dots accumulation at the grains boundaries, dopant accumulation near the QD) highlighting the different phonon scattering mechanisms
- Next step: integration of QDSL into thermoelectric devices



- **EUROPEAN UNION**

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THANK YOU FOR YOUR ATTENTION

Commissariat à l'énergie atomique et aux énergies alternatives
17 rue des Martyrs | 38054 Grenoble Cedex
www-liten.cea.fr

Établissement public à caractère industriel et commercial | RCS Paris B 775 685 019